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S P E J C A L

Sheet 37 of 38

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Attorney Docket No.
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Serial No.
10/053,859

Applicant
Goodson, et al.

Filing Date
01/19/02

Group
3743

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

U.S. PATENT DOCUMENTS

Examiner Initials	Item	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation
							Yes No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

<i>TM</i>	AKA	"Laminar flow through microchannels used for microscale cooling systems", Jiang et al., Proceedings of the Electronic Technology Conference, EPTC; 1997; p.119-122
<i>TM</i>	AKB	"Fabrication of monolithic microchanriels for IC chip cooling", Joo et al., Proceedings of the IEEE Micro Electro Mechanical Systems; 1995; p.362-367
<i>TM</i>	AKC	"Performance test and analysis of silicon-based microchannel heat sink", Kang et al, Proceedings of SPIE - The International Society for Optical Engineering; 1999; v.3795, p.259-270
<i>TM</i>	AKD	"Micro heat exchangers consisting of pin arrays", Yin, et al., Journal of Electronic Packaging, Mar. 1996, v.118, p.51-57
<i>TM</i>	AKE	"Measurements of Heat Transfer in Microchannel Heat Sinks", Rahman, International Communications in Heat and Mass Transfer, May 2000, v.27, no.4, p.495-506
<i>TM</i>	AKF	"Enhancement of Critical Heat Flux From High Power Microelectronic Heat Sources in a Flow Channel", Mudawar, et al., Journal of Electronic Packaging, Sept. 1990, v.132, p.241-248
<i>TM</i>	AKG	"Closed-Loop Electroosmotic Microchannel Cooling System for VLSI Circuits", Jiang, et al., printed in Journal of MEMS, Jan. 2002
<i>TM</i>	AKH	"Liquid Flows in Microchannels", Sharp, et al., CRC Press, 2002, Chapter 6, p.6-1 to 6-38

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		Document Number	Date	Country	Class	Subclass	Translation
							Yes No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

TM	ALA	"Fabrication and characterization of electrokinetic micro pumps", Zeng, et al., 2000 Inter Society Conference on Thermal Phenomena, May 2000, p.31 -35
TM	ALB	"Thermal-hydraulic characteristic of micro heat exchangers", Wang, et al., American Society of Mechanical Engineers, Dynamic Systems and Control Division, DSC, 1991 ,v.32, p.331-339
TM	ALC	"Electrokinetic Generation of High Pressures Using Porous Microstructures", Paul, et al., Micro-total analysis systems, 1998, Banff, Canada 1998, p.49-52

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